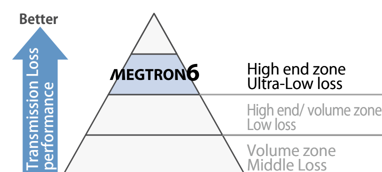
Ultra-low transmission loss Highly heat resistant Multi-layer circuit board materials
超低伝送損失・高耐熱多層基板材料

MEGTRON6
Laminate **R-5775(N)*** **R-5775**
Prepreg **R-5670(N)*** **R-5670**
*Low Dk glass cloth type

Applications 用途

ICT infrastructure equipment, Supercomputer, Measuring instrument, Antenna(Base station, Automotive millimeter-wave radar), Etc.
ICT インフラ機器 (スーパーコンピュータ、計測用機器)、
アンテナ (基地局、車載ミリ波レーダ)、高周波用途など

The industry standard for high speed, ultra-low loss material.
Excellent HDI and thermal performance.
超高性能サーバやルータ向け材料のデファクトスタンダード。
低伝送ロスを実現し、超高性能サーバやルータの性能向上に貢献

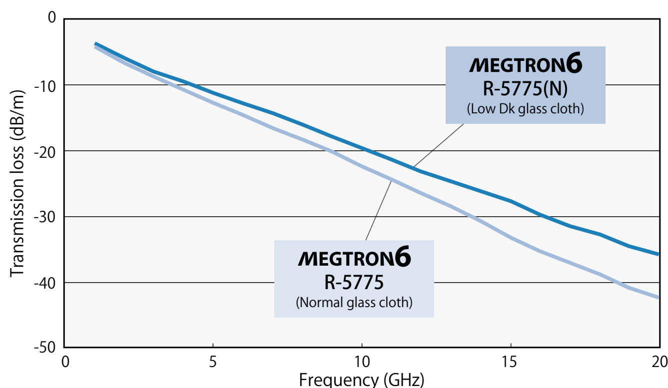


Dk 3.4 Df 0.004 @12GHz

Tg (DSC) 185℃

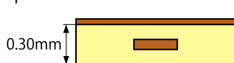
T288 (with copper) >120min

Frequency dependence by Transmission loss 伝送損失比較



● Construction

Stripline



Copper thickness	18 μm
Copper type	H-VLP
Core	0.15mm (#1078 x 2ply)
Prepreg	#1078 x 2ply
Impedance	50Ω

Heat resistance of High Multi-layer 高多層耐熱性

● Result

Drill diameter	φ0.3mm	
Wall to wall distance	0.5mm	0.6mm
MEGTRON6 (Low Dk glass cloth)	pass	pass

● Condition

260℃ reflow x 10times

● Construction

32 Layers
Board thickness: 4.5mm

General properties 一般特性

Item		Test method	Condition	Unit	MEGTRON6 R-5775(N) Low Dk glass cloth	MEGTRON6 R-5775 Normal glass cloth
Glass transition temp.(Tg)		DSC	A	℃	185	185
CTE z-axis	α1	IPC-TM-650 2.4.24	A	ppm/℃	45	45
	α2				260	260
T288(with copper)		IPC-TM-650 2.4.24.1	A	min	>120	>120
Dielectric constant(Dk)	12GHz	Balanced-type circular disk resonator	C-24/23/50	–	3.4	3.6
Dissipation factor(Df)					0.004	0.004
Peel strength*	1oz(35 μm)	IPC-TM-650 2.4.8	A	kN/m	0.8	0.8

The sample thickness is 0.75mm.
* H-VLP Copper

The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。

Please see the page for "Notes before you use" 商品のご採用に当たっての注意事項は こちら

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